

**GaN 50V, 900W, DC-1GHz RF Power Transistor****Description**

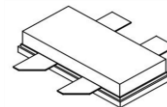
The SK1090RVPS is a 900W, input matched GaN HEMT, ideal for multiple applications from DC-1GHz, with leading efficiency. It can support CW, pulse or any modulated signal.

There is no guarantee of performance when this part is used outside of stated frequencies.

- Typical performance across 0.4-0.7GHz class AB application circuit with device soldered

VDS= 50V, IDQ=200mA(Vgs=-3.25V) Pulsed CW 100us/10%

| F(MHz) | Pin (dBm) | Pout (dBm) | Pout (W) | I(A)  | Gain (dB) | Eff(%) |
|--------|-----------|------------|----------|-------|-----------|--------|
| 400    | 38.5      | 59.5       | 891.3    | 3.2   | 21        | 55.70  |
| 450    | 38.3      | 59.2       | 831.8    | 2.94  | 20.9      | 56.58  |
| 500    | 38.7      | 59.2       | 831.8    | 2.637 | 20.5      | 63.08  |
| 550    | 39.3      | 58.4       | 691.8    | 2.44  | 19.1      | 56.71  |
| 600    | 40.8      | 59.8       | 955.0    | 2.52  | 19        | 75.79  |
| 650    | 41.8      | 59.2       | 831.8    | 2.4   | 17.4      | 69.31  |
| 700    | 42        | 60         | 1000.0   | 2.76  | 18        | 72.46  |

**SK1090RVPS****Applications**

- P band power amplifier
- UHF TV
- Wideband power amplifier
- ISM

**Important Note: Proper Biasing Sequence for GaN HEMT Transistors****Turning the device ON**

1. Set VGS to the pinch-off (VP) voltage, typically -5 V
2. Turn on VDS to nominal supply voltage
3. Increase VGS until IDS current is attained
4. Apply RF input power to desired level

**Turning the device OFF**

1. Turn RF power off
2. Reduce VGS down to VP, typically -5 V
3. Reduce VDS down to 0 V
4. Turn off VGS

**Table 1. Maximum Ratings**

| Rating                         | Symbol           | Value       | Unit |
|--------------------------------|------------------|-------------|------|
| Drain--Source Voltage          | V <sub>DSS</sub> | +200        | Vdc  |
| Gate--Source Voltage           | V <sub>GS</sub>  | -10 to +2   | Vdc  |
| Operating Voltage              | V <sub>DD</sub>  | 55          | Vdc  |
| Maximum gate current           | I <sub>gs</sub>  | 108         | mA   |
| Storage Temperature Range      | T <sub>stg</sub> | -65 to +150 | °C   |
| Case Operating Temperature     | T <sub>c</sub>   | +150        | °C   |
| Operating Junction Temperature | T <sub>J</sub>   | +225        | °C   |

**Table 2. Thermal Characteristics**

| Characteristic   | Symbol           | Value | Unit  |
|--|------------------|-------|-------|
| Thermal Resistance, Junction to Case by FEA<br>T <sub>c</sub> = 85°C, at T <sub>j</sub> =200°C | R <sub>θJC</sub> | 0.3   | °C /W |



**Table 3. Electrical Characteristics (TA = 25°C unless otherwise noted)**

**DC Characteristics (measured on wafer prior to packaging)**

| Characteristic                 | Conditions  | Symbol              | Min | Typ   | Max | Unit |
|--------------------------------|---|---------------------|-----|-------|-----|------|
| Drain-Source Breakdown Voltage | VGS=-8V; IDS=108mA                                  | V <sub>DSS</sub>    |     | 200   |     | V    |
| Gate Threshold Voltage         | VDS =10V, ID = 108mA                                | V <sub>GS(th)</sub> | -4  |       | -2  | V    |
| Gate Quiescent Voltage         | VDS =50V, IDS=200mA,<br>Measured in Functional Test | V <sub>GS(Q)</sub>  |     | -3.25 |     | V    |

**Ruggedness Characteristics**

| Characteristic           | Conditions   | Symbol | Min | Typ | Max | Unit |
|--------------------------|--|--------|-----|-----|-----|------|
| Load mismatch capability | 1GHz, Pout=900W Pulsed CW<br><br>All phase,<br><br>No device damages | VSWR   |     | 5:1 |     |      |

**Figure 2: Network analyzer output, S11 and S21 ( VDS=50V VGS=-3.2V IDQ=500mA)**

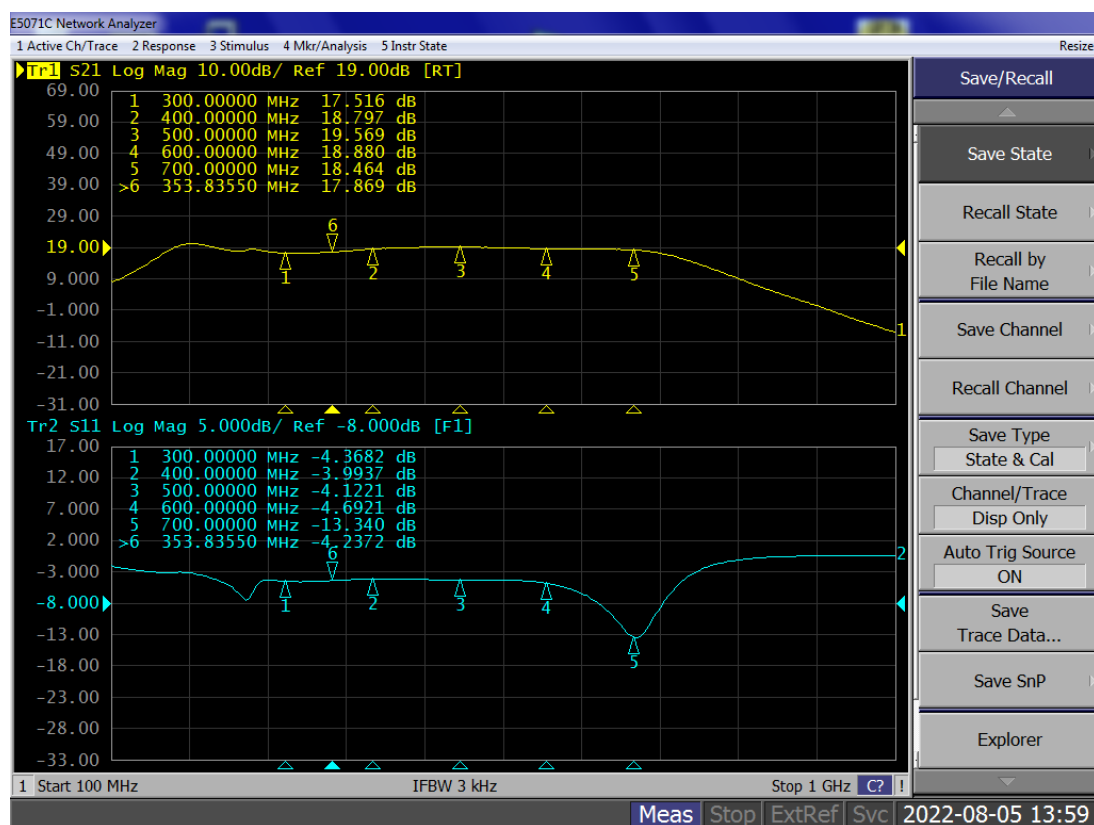


Figure 3: Picture of application board 0.4-0.7GHz class AB

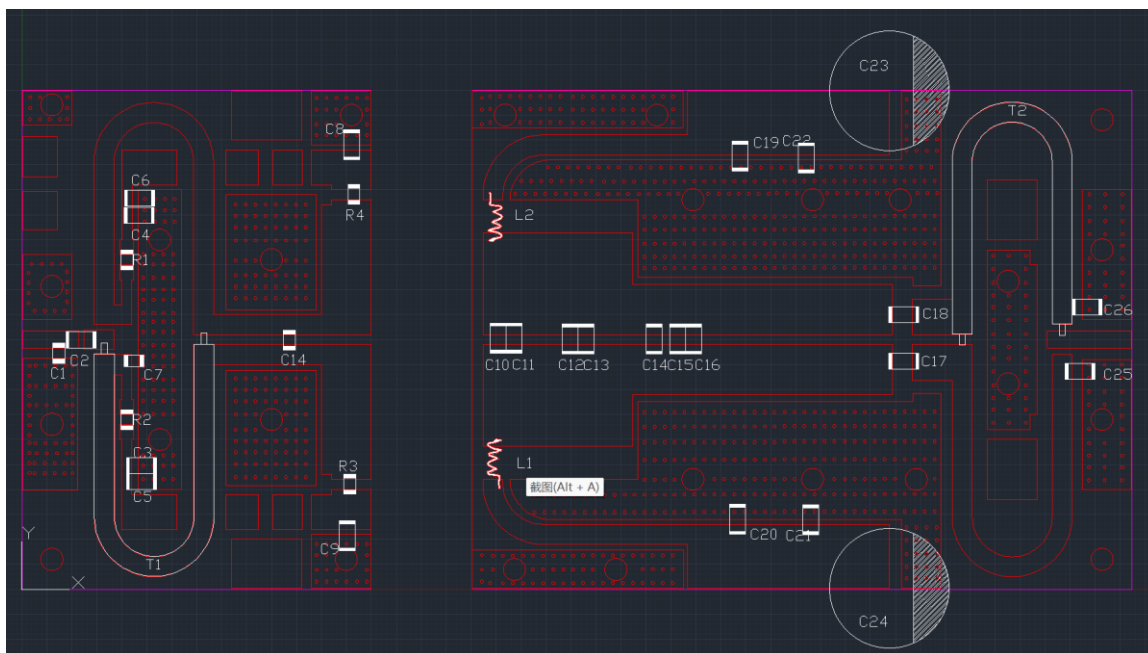
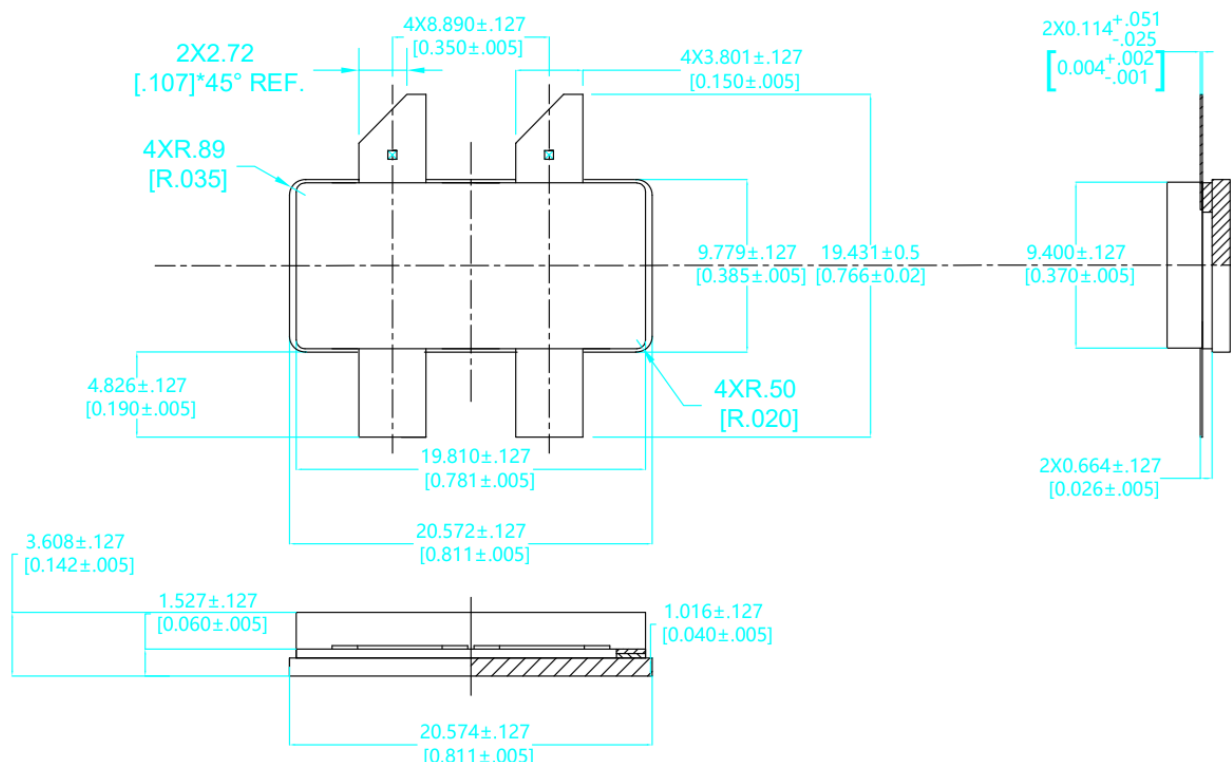


Table 4. Bill of materials of application board (PCB layout upon request)

| Component           | Description                | Suggested Manufacturer |
|---------------------|----------------------------|------------------------|
| C1                  | 2.7pF 100A                 |                        |
| C2、C3、C4、C20、C19    | 300pF 100B                 |                        |
| C5、C6、C21、C22、C8、C9 | 10UF 1210                  |                        |
| C14                 | 20PF 100B                  |                        |
| C7、C25、C26          | 56PF 100B                  |                        |
| C10、C11             | 3.3PF 100B                 |                        |
| C12                 | 3.9PF 100B                 |                        |
| C11                 | 5.1PF 100B                 |                        |
| C14、C16             | 4.7PF 100B                 |                        |
| C15                 | 10PF 100B                  |                        |
| C23、C24             | 钽电容 4700UF 63V             |                        |
| C17、C18             | 8.2PF 100B                 |                        |
| R1、R2、R3、R4         | Chip Resistor,9.1 Ω ,0603  |                        |
| L1、L2               | 自制电感 内径3.0mm Ψ0.67mm漆包线 5圈 |                        |
| T1                  | SFF-25-1.5 50mm            |                        |
| T2                  | SFF-16.7-1.5 50mm          |                        |
| PCB                 | 30mil Rogers4350B          |                        |



## Earless Flanged Ceramic Package; 4 leads



## Revision history

Table 4. Document revision history

| Date       | Revision | Datasheet Status                         |
|------------|----------|--|
| 2022/01/08 | V1.0     | Preliminary Datasheet Creation           |
| 2022/8/5   | V1.1     | Change carrier application to 0.4-0.7GHz |
| 2025/7/2   | V1.2     | Correct the package info from B4 to BY4  |
|            |          |  |

Application data based on: SYX-22-10

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